Amendment under 37 CFR 1.116 Shigeo OHSAKA et al.

U.S. Patent Application S.N. 09/456,531 Attorney Docket No. 991387

2. (Amended) An electrode structure including a conductive film formed on an insulation film, the insulation film being formed on a base substrate,

the insulation film comprising a first film of polyimide having a plurality of openings which reach the base substrate, a second film formed on inside walls of the openings and formed of an insulation material having a higher hardness than polyimide, and a plurality of poles of polyimide buried in the openings with the second film formed on the inside walls thereof.

3. (Amended) A semiconductor light-emitting device having an electrode structure including a conductive film formed on an insulation film, the insulation film being formed on a base substrate,

the insulation film comprising a plurality of poles of polyimide, a first film formed on side surfaces of the poles and formed of an insulation material having a higher hardness than polyimide, and a second film of polyimide buried among said a plurality of poles with the first film formed on side surfaces thereof.

5. (Amended) A semiconductor light-emitting device having an electrode structure including a conductive film formed on an insulating film, the insulation film being formed on a base substrate,

the insulation film comprising a first film of polyimide having a plurality of openings which reach the base substrate, a second film formed on inside walls of the openings and formed of an insulation material having a higher hardness than polyimide, and a plurality of poles of polyimide buried in the openings with the second film formed on the inside walls thereof.

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7. (Twice Amended) A semiconductor light-emitting device according to claim 3, wherein the conductive film is formed on the insulation film through a third film of an insulation material, the third film is formed on the insulation film.

8. (Twice Amended) A semiconductor light-emitting device according to claim 5, wherein the conductive film is formed on the insulation film through a third film of an insulation material, the third film is formed on the insulation film.

13. (Twice Amended) A semiconductor light-emitting device including a waveguide, a lower electrode formed below the waveguide, and an upper electrode formed above the waveguide, the upper electrode having an electrode structure,

the electrode structure including a conductive film formed an insulation film, the insulation film being formed on a base substrate,

the insulation film comprising a plurality of poles of polyimide, a first film formed on side surfaces of the poles and formed of an insulation material having a higher hardness than polyimide, and a second film of polyimide buried among said a plurality of poles with the first film formed on the side surfaces thereof.

14. (Twice Amended) A semiconductor light-emitting device including a waveguide, a lower electrode formed below the waveguide, and an upper electrode formed above the waveguide, the upper electrode having an electrode structure,

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the electrode structure including a conductive film formed on an insulation film, the insulation film being formed on a base substrate,

the insulation film comprising a first film of polyimide having a plurality of openings a first film of polyimide having a plurality of openings which reach the base substrate, a second film formed on inside walls of the openings and formed of an insulation material having a higher hardness than polyimide, and a plurality of poles of polyimide buried in the openings with the second film formed on the inside walls thereof.